

## Patent Abstracts of Japan

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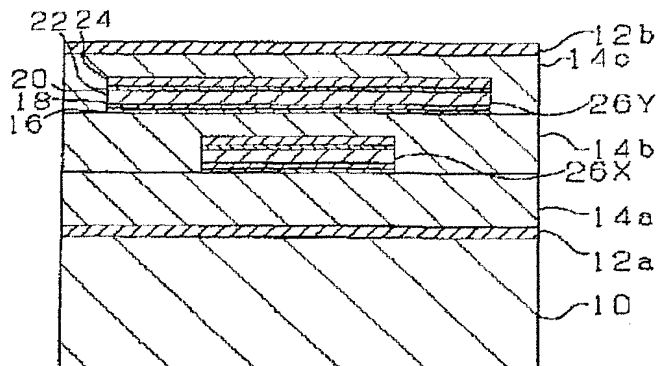
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APPLICANT : NGK SPARK PLUG CO LTD:

INVENTOR : WAKAMATSU SUSUMU:

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TITLE : CIRCUIT BOARD



**ABSTRACT :** PURPOSE: To provide a circuit board with low loss and high signal transmission speed at high frequencies.

**CONSTITUTION:** On a nickel-plated layer 22 which is a magnetic material formed on a copper-plated layer 20, a gold-plated layer 24 which is a non-magnetic material is further formed. Thus when a circuit board is used at high frequencies, though inductance of the nickel-plated layer 22 increases, current flows to the overlying gold-plated layer 24 and to the underlying copper-plated layer 20 due to skin effects, while no current flows to the nickel-plated layer 22 made of the magnetic material located in between, thereby generating no transmission loss due to the nickel-plated layer 22.

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